

Application Data Sheet

Application Information

Application Type::	Regular
Subject Matter::	Utility
Suggested Classification::	
Suggested Group Art Unit::	
CD-ROM or CD_R?::	None
Number of CD disks::	
Number of copies of CDs::	
Sequence Submission::	No
Computer Readable Form (CRF)?::	No
Title::	BONDING LAYER FORMING SOLUTION, METHOD OF PRODUCING COPPER-TO-RESIN BONDING LAYER USING THE SOLUTION, AND LAYERED PRODUCT OBTAINED THEREBY
Attorney Docket Number::	10873.1436US01
Request For Early Publication::	No
Request For Non-Publication::	No
Suggested Drawing Figure::	1
Total Drawing Sheets::	1
Small Entity::	Yes
Latin Name::	
Variety Denomination Name::	
Petition Included::	No
Petition Type::	
Licensed US Govt. Agency::	
Contract or Grant Numbers::	
Secrecy Order in Parent Appl.?::	No

Initial April 16, 2004

Applicant Information

Applicant Authority Type::	Inventor
Primary Citizenship Country::	Japan
Status::	Full Capacity
Given Name::	Mutsuyuki
Middle Name::	
Family Name::	KAWAGUCHI
Name Suffix::	
City of Residence::	Amagasaki-shi
State or Province of Residence::	Hyogo
Country of Residence::	Japan
Street of mailing address::	c/o MEC COMPANY LTD., 1, Higashihatsushima-cho
City of mailing address::	Amagasaki-shi
State or Province of mailing address::	Hyogo
Country of mailing address::	Japan
Postal or Zip Code of mailing address::	660-0832

Applicant Information

Applicant Authority Type::	Inventor
Primary Citizenship Country::	Japan
Status::	Full Capacity
Given Name::	Satoshi
Middle Name::	
Family Name::	SAITO
Name Suffix::	
City of Residence::	Amagasaki-shi
State or Province of Residence::	Hyogo
Country of Residence::	Japan
Street of mailing address::	c/o MEC COMPANY LTD., 1, Higashihatsushima-cho
City of mailing address::	Amagasaki-shi
State or Province of mailing address::	Hyogo
Country of mailing address::	Japan
Postal or Zip Code of mailing address::	660-0832

Applicant Information

Applicant Authority Type::	Inventor
Primary Citizenship Country::	Japan
Status::	Full Capacity
Given Name::	Jun
Middle Name::	
Family Name::	HISADA
Name Suffix::	
City of Residence::	Amagasaki-shi
State or Province of Residence::	Hyogo
Country of Residence::	Japan
Street of mailing address::	c/o MEC COMPANY LTD., 1, Higashihatsushima-cho
City of mailing address::	Amagasaki-shi
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Postal or Zip Code of mailing address::	660-0832

Applicant Information

Applicant Authority Type::	Inventor
Primary Citizenship Country::	Japan
Status::	Full Capacity
Given Name::	Naomi
Middle Name::	
Family Name::	KANDA
Name Suffix::	
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State or Province of Residence::	Hyogo
Country of Residence::	Japan
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Postal or Zip Code of mailing address::	660-0832

Applicant Information

Applicant Authority Type::	Inventor
Primary Citizenship Country::	Japan
Status::	Full Capacity
Given Name::	Toshiko
Middle Name::	
Family Name::	NAKAGAWA
Name Suffix::	
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State or Province of Residence::	Hyogo
Country of Residence::	Japan
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City of mailing address::	Amagasaki-shi
State or Province of mailing address::	Hyogo
Country of mailing address::	Japan
Postal or Zip Code of mailing address::	660-0832

Correspondence Information

Correspondence Customer Number:: 23552

Representative Information

Representative Customer Number::	23552
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Foreign Priority Information

Country::	Application Number::	Filing Date::	Priority Claimed::
Japan	2003-125631	April 30, 2003	Yes
Japan	2003-164183	June 9, 2003	Yes

Assignee Information

Assignee Name:: MEC COMPANY LTD.
Street of mailing address:: 1, Higashihatsushima-cho
City of mailing address:: Amagasaki-shi
State or Province of mailing address:: Hyogo
Country of mailing address:: Japan
Postal or Zip Code of mailing address:: 660-0832

Initial April 16, 2004